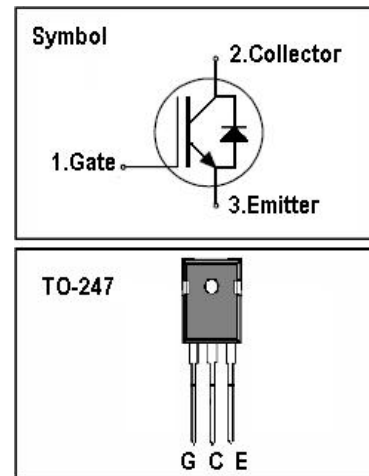


Features

- 650V 60A, $V_{CE(sat)(typ.)} = 2.3 \text{ V}@60\text{A}$
- Field Stop IGBT Technology.
- 10 μs Short Circuit Capability.
- Square RBSOA.
- Positive V_{CE} (on) Temperature Coefficient.

Benefits

- High Efficiency for Welding, Inductive heating, UPS and other high frequency application
- Rugged Performance
- Excellent Current Sharing in Parallel Operation



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Continuous Collector Current ($T_C=25^\circ\text{C}$)	120	A
	Continuous Collector Current ($T_C=100^\circ\text{C}$)	60	A
I_{CM}	Pulsed Collector Current (Note 1)	240	A
I_F	Diode Continuous Forward Current ($T_C=100^\circ\text{C}$)	60	A
I_{FM}	Diode Maximum Forward Current (Note 1)	240	A
t_{sc}	Short Circuit Withstand Time	10	μs
I_{sc}	Short Circuit Current	270	A
P_D	Maximum Power Dissipation ($T_C=25^\circ\text{C}$)	378	W
P_D	Maximum Power Dissipation ($T_C=100^\circ\text{C}$)	151	W
T_J	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th j-c}$	Thermal Resistance, Junction to case for IGBT	0.33	$^\circ\text{C}/\text{W}$
$R_{th j-c}$	Thermal Resistance, Junction to case for Diode	0.65	$^\circ\text{C}/\text{W}$
$R_{th j-a}$	Thermal Resistance, Junction to Ambient	80	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_C=25 °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	650	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 650V, V _{GE} = 0V	-	-	250	uA
I _{GES}	Gate Leakage Current, Forward	V _{GE} = 30V, V _{CE} = 0V	-	-	100	nA
	Gate Leakage Current, Reverse	V _{GE} = -30V, V _{CE} = 0V	-	-	-100	nA
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 250uA	4.0	-	5.5	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} = 15V, I _C = 40A	-	2.3		V
Q _g	Total Gate Charge	V _{CC} = 480V V _{GE} = 15V I _C = 60A	-	210		nC
Q _{ge}	Gate-Emitter Charge		-	28		nC
Q _{gc}	Gate-Collector Charge		-	115		nC
t _{d(on)}	Turn-on Delay Time	V _{CC} = 400V V _{GE} = 15V I _C = 60A R _G = 10Ω Inductive Load T _C = 25 °C	-	31	-	ns
t _r	Turn-on Rise Time		-	82	-	ns
t _{d(off)}	Turn-off Delay Time		-	196	-	ns
t _f	Turn-off Fall Time		-	60	-	ns
E _{on}	Turn-on Switching Loss		-	2.55	-	mJ
E _{off}	Turn-off Switching Loss		-	1.75	-	mJ
C _{ies}	Input Capacitance	V _{CE} = 25V	-	2020	-	pF
C _{oes}	Output Capacitance	V _{GE} = 0V	-	280	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz	-	130	-	pF
R _{Gint}	Integrated gate resistor	f = 1MHz; V _{pp} = 1V		1.55		Ω

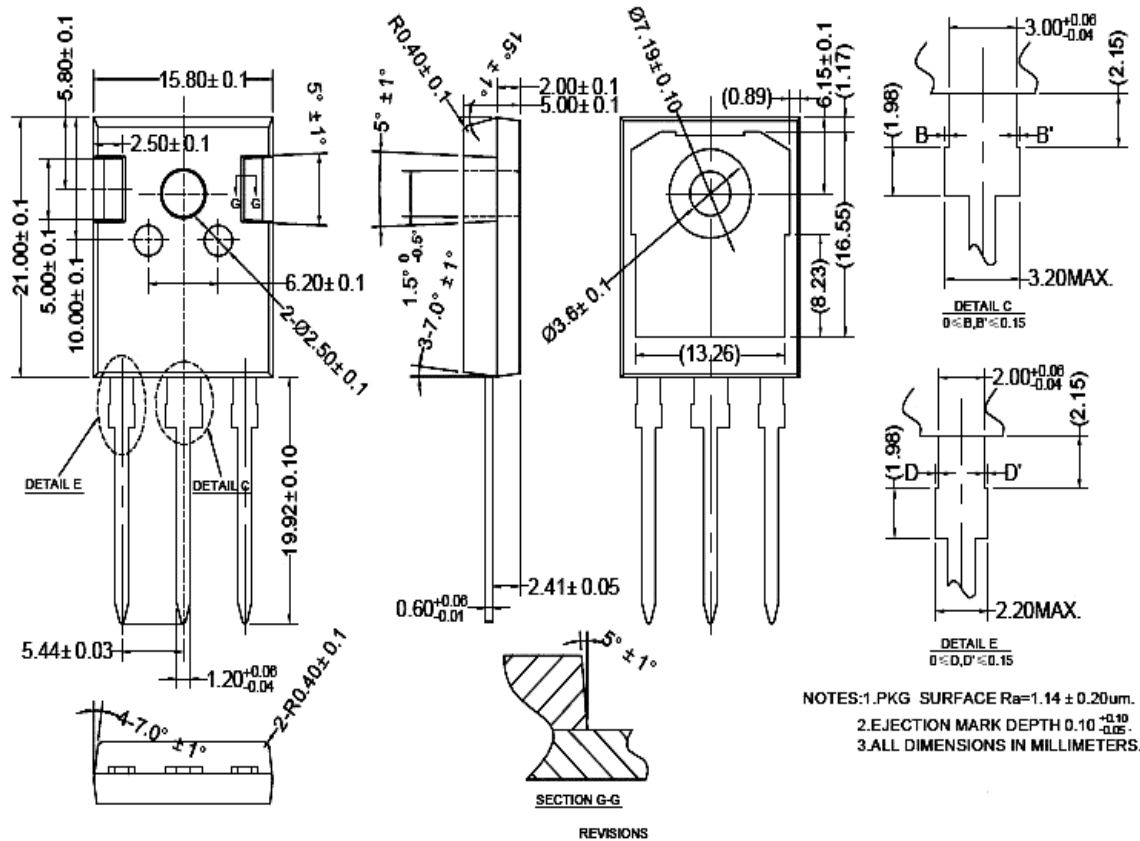
Electrical Characteristics of Diode (T_C=25 °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _F	Diode Forward Voltage	I _F = 60A	-	1.35		V
t _{rr}	Diode Reverse Recovery Time	V _{CE} = 400V	-	150		ns
I _{rrm}	Diode peak Reverse Recovery Current	I _F = 60A	-	22		A
Q _{rr}	Diode Reverse Recovery Charge	dI _F /dt = 500A/us	-	1320		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

TO247 PACKAGE OUTLINE



公差标注	公差值	表面粗糙度
0	±0.2	Ra3.2~6.3
0.0	±0.1	Ra1.6~3.2
0.00	±0.01	Ra0.8~1.6
0.000	±0.005	Ra0.4~0.8
0.0000	±0.002	Ra0.2~0.4

0≤D,D'≤0.15

NOTES: 1. PKG SURFACE Ra=1.14±0.20µm.
2. EJECTION MARK DEPTH 0.10^{+0.10/-0.05}.
3. ALL DIMENSIONS IN MILLIMETERS.